



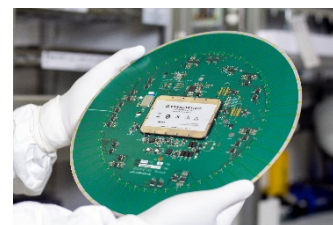
CyberOptics Features High-Precision Sensor Technology at Virtual SEMICON Japan

Sensors save time, save expense and improve yields in semiconductor fabs

Minneapolis, Minnesota — December, 2020 — [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high-precision 3D sensing technology solutions, will exhibit at the virtual SEMICON Japan, December 14-17. During the show, the company will feature its new In-Line Particle Sensor™ (IPS) and Auto Resistance Sensor™ (ARS) for semiconductor tool set-up and equipment diagnostics, and the WX3000™ Metrology and Inspection system for wafer-level and advanced packaging applications.

Minimizing particles in semiconductor fab environments is vital. Stringent manufacturing requirements and a focus on maximizing yields and tool uptimes drives the need for best-in-class practices for a contamination-free process environment. The new [In-Line Particle Sensor](#) (IPS) with CyberSpectrum™ software detects particles in gas and vacuum lines 24/7 in semiconductor process equipment and is an extension of the industry-leading WaferSense® and ReticleSense® Airborne Particle Sensor (APS) technology that is documented by fabs as the Best Known Method (BKM). The IPS quickly identifies, monitors and enables troubleshooting of particles down to 0.1µm. Contamination sources can be quickly identified and the effects of cleaning, adjustments and repairs can be seen in real-time.

For tools set-up and diagnostics, the WaferSense® [Auto Resistance Sensor™](#) (ARS) with CyberSpectrum™ software enables real-time resistance measurements of plating cell contacts in semiconductor Electrochemical Deposition (ECD) applications. With ARS, engineers can predict when a tool needs maintenance with quantitative analysis of measured mean resistance over time, and improve cell-to-cell process uniformity.



Process and equipment engineers in semiconductor fabs can speed equipment qualification, shorten equipment maintenance cycles, lower equipment expenses and optimize preventative maintenance plans.

For wafer-level and advanced packaging metrology and inspection, the new [WX3000™](#) system will be highlighted. Performing two to three times faster than alternate technologies at data processing speeds in excess of 75 million 3D data points per second, the WX3000 system with [NanoResolution Multi-Reflection Suppression™](#) (MRS™) sensor technology deliver throughput greater than 25 wafers per hour. 100% 3D and 2D metrology and inspection can be completed simultaneously at high speed, as compared to an alternate, slow method that requires two separate scans for 3D and 2D and only a sampling method.



The proprietary NanoResolution MRS sensor, deemed best in class, meticulously identifies and rejects multiple reflections caused by shiny and mirror-like surfaces. Effective suppression of multiple reflections is critical for highly accurate measurements.

For more information, visit www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high-precision 3D sensing technology solutions. CyberOptics' sensors are used for inspection and metrology in the SMT and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the Company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: a possible world-wide recession or depression resulting from the economic consequences of the COVID-19 pandemic; the negative effect on our revenue and operating results of the COVID-19 crisis on our customers and suppliers and the global supply chain; market conditions in the global SMT and semiconductor capital equipment industries; trade relations between the United States and China and other countries; the timing of orders and shipments of our products, particularly our 3D MRS-enabled SQ3000 Multi-Function systems and MX systems for memory module inspection; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 Multi-Function inspection and measurement systems and products for semiconductor advanced packaging inspection and metrology; costly and time consuming litigation with third parties related to intellectual property infringement; the negative impact on our customers and suppliers due to past and future terrorist threats and attacks and any acts of war; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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